

#### GENERAL DESCRIPTION

The Oki MSC2320A-xxYS9 is a fully decoded, 262,144 word  $\times$  36 bit CMOS dynamic random access memory composed of eight 1Mb DRAMs in SOJ (MSM514256AJS) and four 256 Kb DRAMs in PLCC (MSM51C256JS). The mounting of eight SOJs and four PLCCs together with twelve 0.2  $\mu$ F decoupling capacitors on a 72 pin glass epoxy Single-In-Line Package supports any application where high density and large capacity of storage memory are required. The electrical characteristics of the MSC2320A-xxYS9 are same as the original MSM514256AJS; each timing requirements are noncritical, and power supply tolerance is very wide.

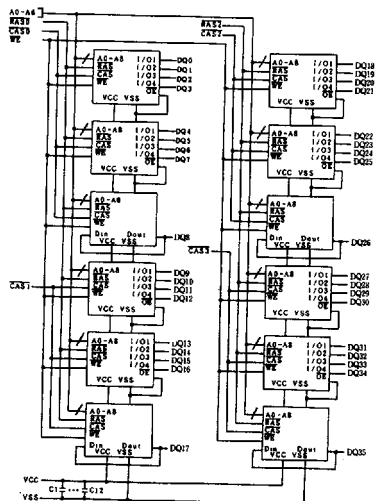
#### FEATURES

- 262,144 word  $\times$  36 bit organization
- JEDEC Compatible Dimensioning
- Family organization

Family	Access Time (MAX)			Cycle Time (MIN)	Power Dissipation	
	t <sub>RAC</sub>	t <sub>AA</sub>	t <sub>CAC</sub>		Operating (MAX)	Standby (MAX)
MSC2320A-80YS9	80ns	40ns	20ns	160ns	4410mW	95mW
MSC2320A-10YS9	100ns	50ns	25ns	190ns	3780mW	(MOS level)

- Single + 5V supply,  $\pm$ 5% tolerance
- Input : TTL compatible
- Output : TTL compatible, tristate, nonlatch
- Refresh : 512 cycles/8 ms
- CAS before RAS refresh, RAS only refresh, hidden refresh, and fast page mode capability
- Fast access and cycle times

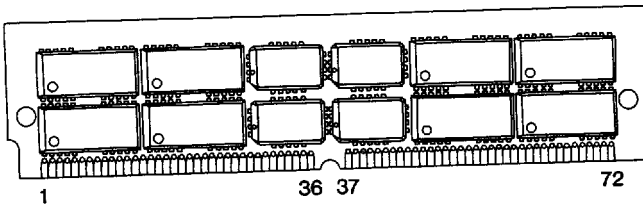
#### FUNCTIONAL BLOCK DIAGRAM



MSC2320A-xxYS9

www.DataSheet4U.com

TOP



PIN No.	PIN NAME	PIN No.	PIN NAME	PIN No.	PIN NAME	PIN No.	PIN NAME	PIN No.	PIN NAME
1	VSS	16	A4	31	A8.	46	NC	61	DQ14
2	DQ0	17	A5	32	NC	47	WE	62	DQ33
3	DQ18	18	A6	33	NC	48	NC	63	DQ15
4	DQ1	19	NC	34	RAS2	49	DQ9	64	DQ34
5	DQ19	20	DQ4	35	DQ26	50	DQ27	65	DQ16
6	DQ2	21	DQ22	36	DQ8	51	DQ10	66	NC
7	DQ20	22	DQ5	37	DQ17	52	DQ28	67	PD0
8	DQ3	23	DQ23	38	DQ35	53	DQ11	68	PD1
9	DQ21	24	DQ6	39	VSS	54	DQ29	69	PD2
10	VCC	25	DQ24	40	CAS0	55	DQ12	70	PD3
11	NC	26	DQ7	41	CAS2	56	DQ30	71	NC
12	A0	27	DQ25	42	CAS3	57	DQ13	72	VSS
13	A1	28	A7	43	CAS1	58	DQ31		
14	A2	29	NC	44	RAS0	59	VCC		
15	A3	30	VCC	45	NC	60	DQ32		

Pin No.	Pin Name	MSC2320A-80YS9	MSC2320A-10YS9
67	PD0	VSS	VSS
68	PD1	N.C.	N.C.
69	PD2	N.C.	VSS
70	PD3	VSS	VSS

**ABSOLUTE MAXIMUM RATINGS** (See Note)

Rating	Symbol	Value	Unit
Voltage on any pin relative to VSS	V <sub>IN</sub> , V <sub>OUT</sub>	-1 ~ +7	V
Voltage on VCC supply relative to VSS	VCC	-1 ~ +7	V
Operating temperature	T <sub>opr</sub>	0 ~ 70	°C
Storage temperature	T <sub>stg</sub>	-40 ~ 125	°C
Power dissipation	P <sub>D</sub>	12	W
Short circuit output current	I <sub>OS</sub>	50	mA

**Note:** Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are Exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# RECOMMENDED OPERATING CONDITIONS (Referenced to V<sub>SS</sub>)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Operating temperature
Supply Voltage	V <sub>CC</sub>	4.75	5.0	5.25	V	0°C ~ +70°C
	V <sub>SS</sub>	0	0	0	V	
Input High Voltage, all inputs	V <sub>IH</sub>	2.4	—	6.25	V	
Input Low Voltage, all inputs	V <sub>IL</sub>	-1.0	—	0.8	V	

## DC CHARACTERISTICS

(V<sub>CC</sub>=5V±5%, T<sub>a</sub>=0~+70°C)

Parameter	Symbol	Condition	MSC2320A-80YS9		MSC2320A-10YS9		Unit	Note
			Min.	Max.	Min.	Max.		
Input Leakage Current	I <sub>LI</sub>	0V ≤ V <sub>IN</sub> ≤ 6.25V : All other pins not under test = 0V	-120	120	-120	120	μA	
Output Leakage Current	I <sub>LO</sub>	Data out is disable 0V ≤ V <sub>OUT</sub> ≤ 5.25V	-10	10	-10	10	μA	
Output high voltage	V <sub>OH</sub>	I <sub>OH</sub> = -5.0mA	2.4	—	2.4	—	V	
Output low voltage	V <sub>OL</sub>	I <sub>OL</sub> = 4.2mA	—	0.4	—	0.4	V	
Average power supply current (Operating)	I <sub>CC1</sub>	$\overline{RAS0}$ , $\overline{RAS2}$ cycling, CAS0-CAS3 cycling, t <sub>RC</sub> = min	—	840	—	720	mA	1, 2
Power supply current (Standby)	I <sub>CC2</sub>	$\overline{RAS0}$ , $\overline{RAS2} = V_{IH}$ TTL	—	30	—	30	mA	
		CAS0-CAS3 = V <sub>IH</sub> MOS	—	18	—	18	mA	
Average power supply current (RAS only refresh)	I <sub>CC3</sub>	$\overline{RAS0}$ , $\overline{RAS2} = V_{IH}$ , CAS0-CAS3 = V <sub>IH</sub> t <sub>RC</sub> = min	—	840	—	720	mA	1, 2
Average power supply current (CAS before RAS refresh)	I <sub>CC6</sub>	t <sub>RC</sub> = min.	—	840	—	720	mA	1
Average power supply current (Fast page mode)	I <sub>CC7</sub>	$\overline{RAS0}$ , $\overline{RAS2} = V_{IL}$ , CAS0-CAS3 cycling t <sub>PC</sub> = min.	—	680	—	620	mA	1, 3

Note : 1. I<sub>CC</sub> in dependent on out put loading and cycle rates.

Specified value are obtained with the output open.

2. Address can be changed once or less while  $\overline{RAS} = V_{IL}$ .

3. Address can be changed once or less while  $\overline{CAS} = V_{IH}$ .

# CAPACITANCE

O K I SEMICONDUCTOR GROUP

 $(V_{CC} = 5V \pm 5\%, f = 1MHz, T_a = 0 \sim +70^{\circ}C)$ [www.DataSheet4U.com](http://www.DataSheet4U.com)

Parameter	Symbol	Min.	Max.	Unit
Input Capacitance (A0 – A8)	$C_{IN1}$	—	88	pF
Input Capacitance ( $\overline{WE}$ )	$C_{IN2}$	—	104	pF
Input Capacitance ( $\overline{RAS0}, \overline{RAS2}$ )	$C_{IN3}$	—	57	pF
Input Capacitance ( $\overline{CAS0} - \overline{CAS3}$ )	$C_{IN4}$	—	36	pF
I/O Capacitance (DQ0–7, 9–16, 18–25, 27–34)	$CDQ_1$	—	17	pF
I/O Capacitance (DQ8, 17, 26, 35)	$CDQ_2$	—	22	pF

[www.DataSheet4U.com](http://www.DataSheet4U.com)

Capacitance measured with Boonton Meter.

# AC CHARACTERISTICS

0

(V<sub>CC</sub> = 5V ± 5%, T<sub>a</sub> = 0 ~ +70°C)

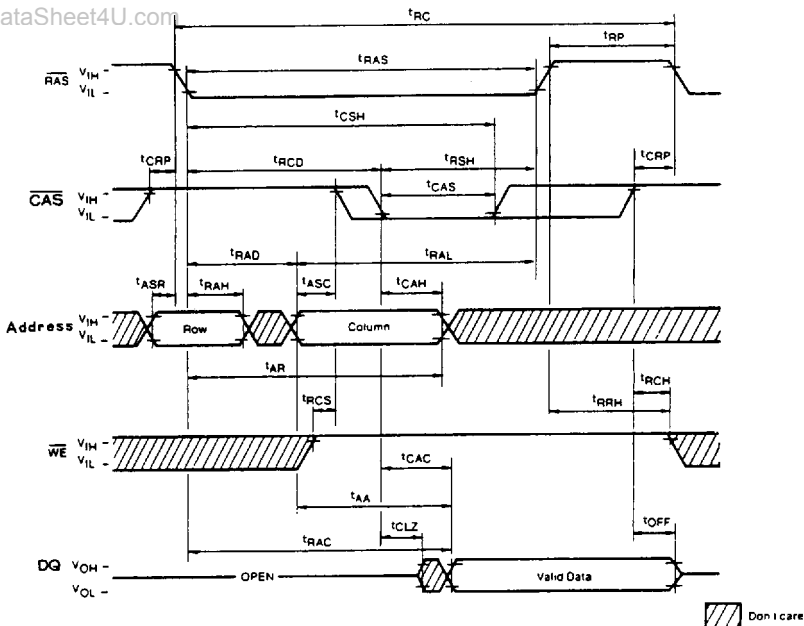
www.DataSheet4U.com

Parameter	Symbol	MSC2320A-80YS9		MSC2320A-10YS9		Unit	Note
		MIN	MAX	MIN	MAX		
Random read or write cycle time	t <sub>RC</sub>	160	—	190	—	ns	
Fast page mode cycle time	t <sub>PC</sub>	50	—	55	—	ns	
Access time from $\overline{\text{RAS}}$	t <sub>RAC</sub>	—	80	—	100	ns	2, 7
Access time from $\overline{\text{CAS}}$	t <sub>CAC</sub>	—	20	—	25	ns	2, 7
Access time from column address	t <sub>AA</sub>	—	40	—	50	ns	2, 8
Access time from $\overline{\text{CAS}}$ precharge	t <sub>CPA</sub>	—	45	—	50	ns	2
$\overline{\text{CAS}}$ to output in Lo-Z	t <sub>CLZ</sub>	0	—	0	—	ns	2
Output buffer turn-off delay	t <sub>OFF</sub>	0	20	0	20	ns	3
Transition time (Rise and Fall)	t <sub>T</sub>	3	50	3	50	ns	1
$\overline{\text{RAS}}$ precharge time	t <sub>RP</sub>	70	—	80	—	ns	
$\overline{\text{RAS}}$ pulse width	t <sub>TRAS</sub>	80	10K	100	10K	ns	
$\overline{\text{RAS}}$ pulse width (Fast page mode)	t <sub>RASP</sub>	80	100K	100	100K	ns	
$\overline{\text{RAS}}$ hold time	t <sub>RSH</sub>	20	—	25	—	ns	
$\overline{\text{CAS}}$ hold time	t <sub>CSH</sub>	80	—	100	—	ns	
$\overline{\text{CAS}}$ pulse width	t <sub>CAS</sub>	20	10K	25	10K	ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ delay time	t <sub>RCD</sub>	22	60	25	75	ns	7
$\overline{\text{RAS}}$ to column address delay time	t <sub>RAD</sub>	17	40	20	50	ns	8
$\overline{\text{CAS}}$ to $\overline{\text{RAS}}$ precharge time	t <sub>CRP</sub>	10	—	10	—	ns	
$\overline{\text{CAS}}$ precharge time (Fast page mode)	t <sub>CP</sub>	10	—	10	—	ns	
Row address set-up time	t <sub>ASR</sub>	0	—	0	—	ns	
Row address hold time	t <sub>RAH</sub>	12	—	15	—	ns	
Column address set-up time	t <sub>ASC</sub>	0	—	0	—	ns	
Column address hold time	t <sub>CAH</sub>	15	—	20	—	ns	
Column address hold time refer. to $\overline{\text{RAS}}$	t <sub>AR</sub>	60	—	75	—	ns	
Column address to $\overline{\text{RAS}}$ lead time	t <sub>RAL</sub>	40	—	50	—	ns	
Read command set-up	t <sub>RCS</sub>	0	—	0	—	ns	
Read command hold time	t <sub>RCH</sub>	0	—	0	—	ns	4
Read command hold time refer. to $\overline{\text{RAS}}$	t <sub>RRH</sub>	10	—	10	—	ns	4
Write command hold time	t <sub>WCH</sub>	15	—	20	—	ns	
Write command hold time refer. to $\overline{\text{RAS}}$	t <sub>WCR</sub>	65	—	75	—	ns	
Write command pulse width	t <sub>WP</sub>	15	—	20	—	ns	
Date set-up time	t <sub>DS</sub>	0	—	0	—	ns	5
Date hold time	t <sub>DH</sub>	15	—	20	—	ns	5
Date hold time referenced to $\overline{\text{RAS}}$	t <sub>DHR</sub>	65	—	75	—	ns	
Refresh period	t <sub>REF</sub>	—	8	—	8	ms	
Write command set-up time	t <sub>WCS</sub>	0	—	0	—	ns	6
$\overline{\text{CAS}}$ set-up time ( $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ cycle)	t <sub>CSR</sub>	10	—	10	—	ns	
$\overline{\text{CAS}}$ hold time ( $\overline{\text{CAS}}$ before $\overline{\text{RAS}}$ cycle)	t <sub>CHR</sub>	30	—	30	—	ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ precharge time	t <sub>RPC</sub>	10	—	10	—	ns	
$\overline{\text{CAS}}$ precharge time	t <sub>CPN</sub>	10	—	15	—	ns	

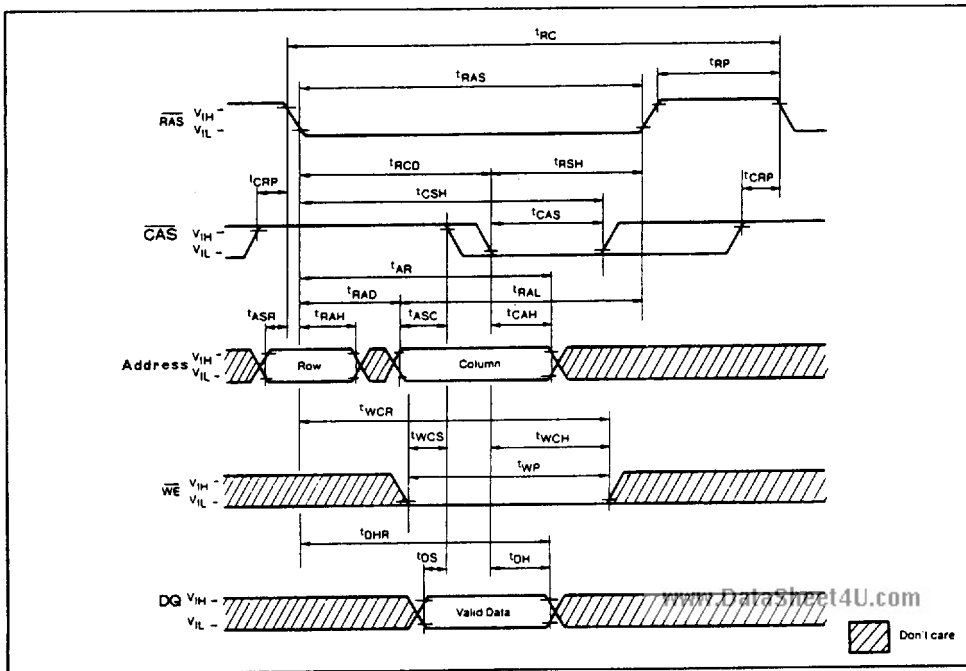
## NOTES :

- 1) AC measurements assume t<sub>r</sub> = 5ns.
- 2) Measured with a load equivalent to 2 TTL loads and 100pf.
- 3) t<sub>OFF</sub> (max) defines the time at which the output achieves an open circuit condition.
- 4) Either t<sub>RCH</sub> or t<sub>RRH</sub> must be satisfied for a read cycle.
- 5) These parameters are referenced to  $\overline{\text{CAS}}$  leading edge.
- 6) t<sub>WCS</sub> is not a restictive operating parameter. This is included in the data sheet as electrical characteristic only. If t<sub>WCS</sub> > t<sub>WCS</sub> (min), the cycle is and early write cycle and the data out pin will remain as open circuit (Hi-Z)
- 7) Operation within the t<sub>RCD</sub> (max) limit, insures that t<sub>RAC</sub> (max) can be met. t<sub>RCD</sub> (max) is specified as a reference point only: if t<sub>RCD</sub> is greater than the specified t<sub>RCD</sub> (max) limit, then access time is controlled by t<sub>CAC</sub>.
- 8) Operation within the t<sub>RAD</sub> (max) limit, insures that t<sub>RAC</sub> (max) can be met. t<sub>RAD</sub> (max) is specified as a reference point only: if t<sub>RAD</sub> is greater than the specified t<sub>RAD</sub> (max) limit, then access time is controlled by t<sub>AA</sub>.

www.DataSheet4U.com



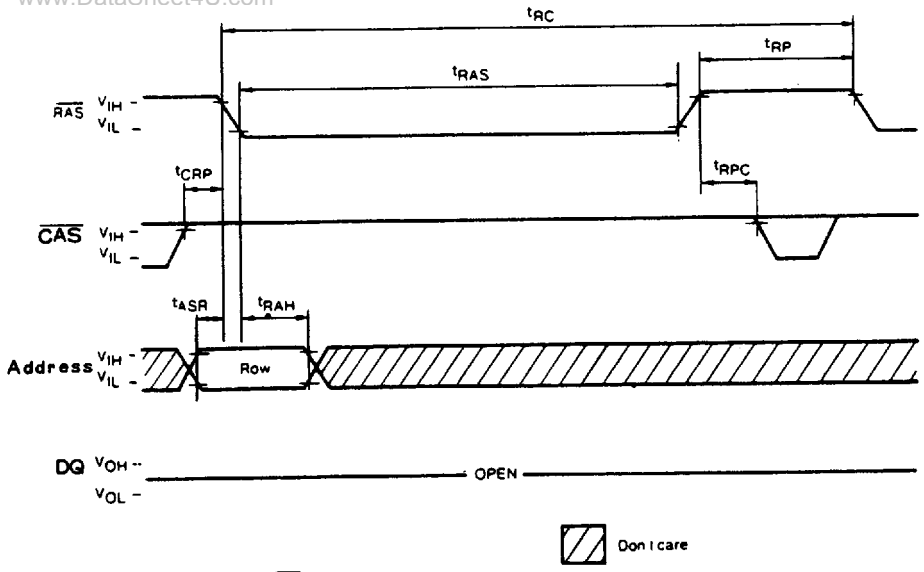
● WRITE CYCLE (EARLY WRITE)





# ● RAS ONLY REFRESH CYCLE

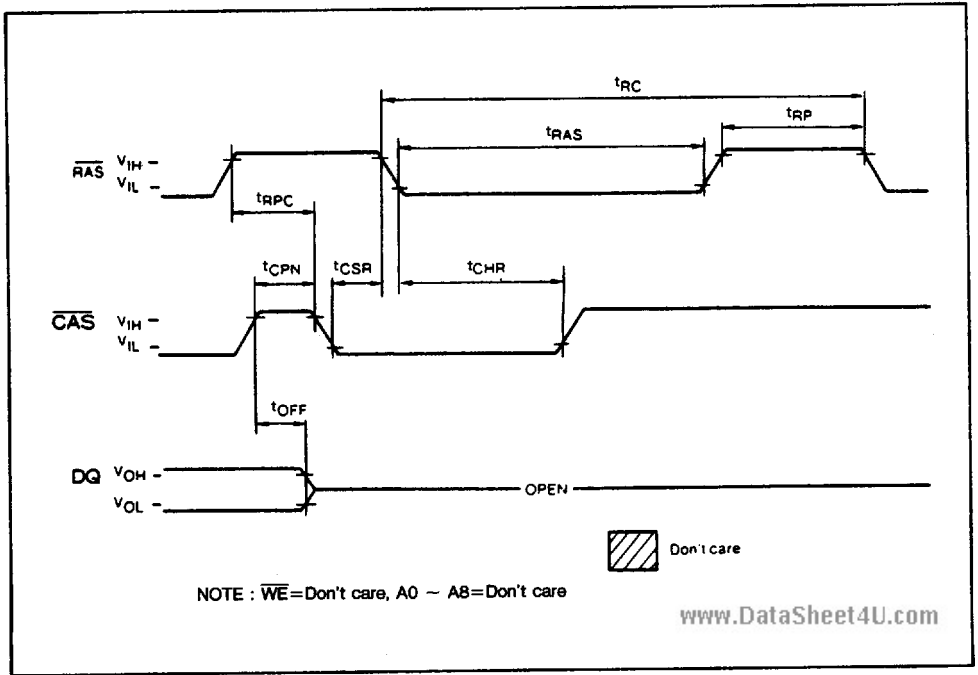
www.DataSheet4U.com



NOTE  $\overline{WE}$  = Don't care.

Don't care

# ● CAS BEFORE RAS REFRESH CYCLE



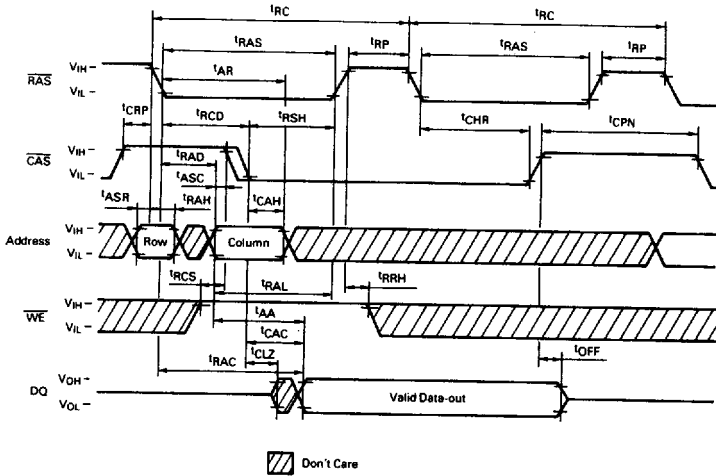
NOTE :  $\overline{WE}$  = Don't care, A0 ~ A8 = Don't care

Don't care



# ● HIDDEN REFRESH READ CYCLE

www.DataSheet4U.com



# ● HIDDEN REFRESH WRITE CYCLE

